

02/25/02

A

Page 1

PATENT

Docket No. JCLA8894

Date: 2-20-2002



ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

ATTENTION: APPLICATION BRANCH

Sir:

Transmitted herewith for filing under 37 C.F.R. 1.53(b) is the patent application of

Inventor(s): HIROSHI SAWADA

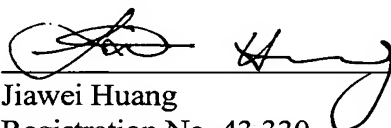
For: **SUBSTRATE CUTTING METHOD**

Enclosed are:

- (X) Specification in (25) pages.
- (X) (13) sheets of drawings.
- (X) Return prepaid postcard.

Note:

THIS APPLICATION IS FILED UNSIGNED AND UNPAID


Jiawei Huang
Registration No. 43,330

Please send communications to:

J.C. Patents
4 Venture, Suite 250
Irvine, California 92618
Tel.: (949) 660-0761
Fax: (949)-660-0809



10084761.022002



J.C. PATENTS, INC.
4 VENTURE, SUITE 250
IRVINE, CALIFORNIA 92618
TEL. (949) 660-0761
FAX (949) 660-0809

Assistant Commissioner for Patents
Washington, D.C. 20231

CERTIFICATE OF MAILING BY "EXPRESS MAIL"

Docket No. : JCLA8894
Inventor(s) : HIROSHI SAWADA ;
For : SUBSTRATE CUTTING METHOD
"Express Mail"
Mailing Label No. : EL 857834661 US
Date of Deposit : February 20, 2002

I hereby certify that the accompanying

Transmittal in Duplicate; Specification in 25 page(s); 13 Pages of Drawings;
Return Prepaid Postcard

are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and are addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

M. Chang

Michelle Chang

10084761-022002